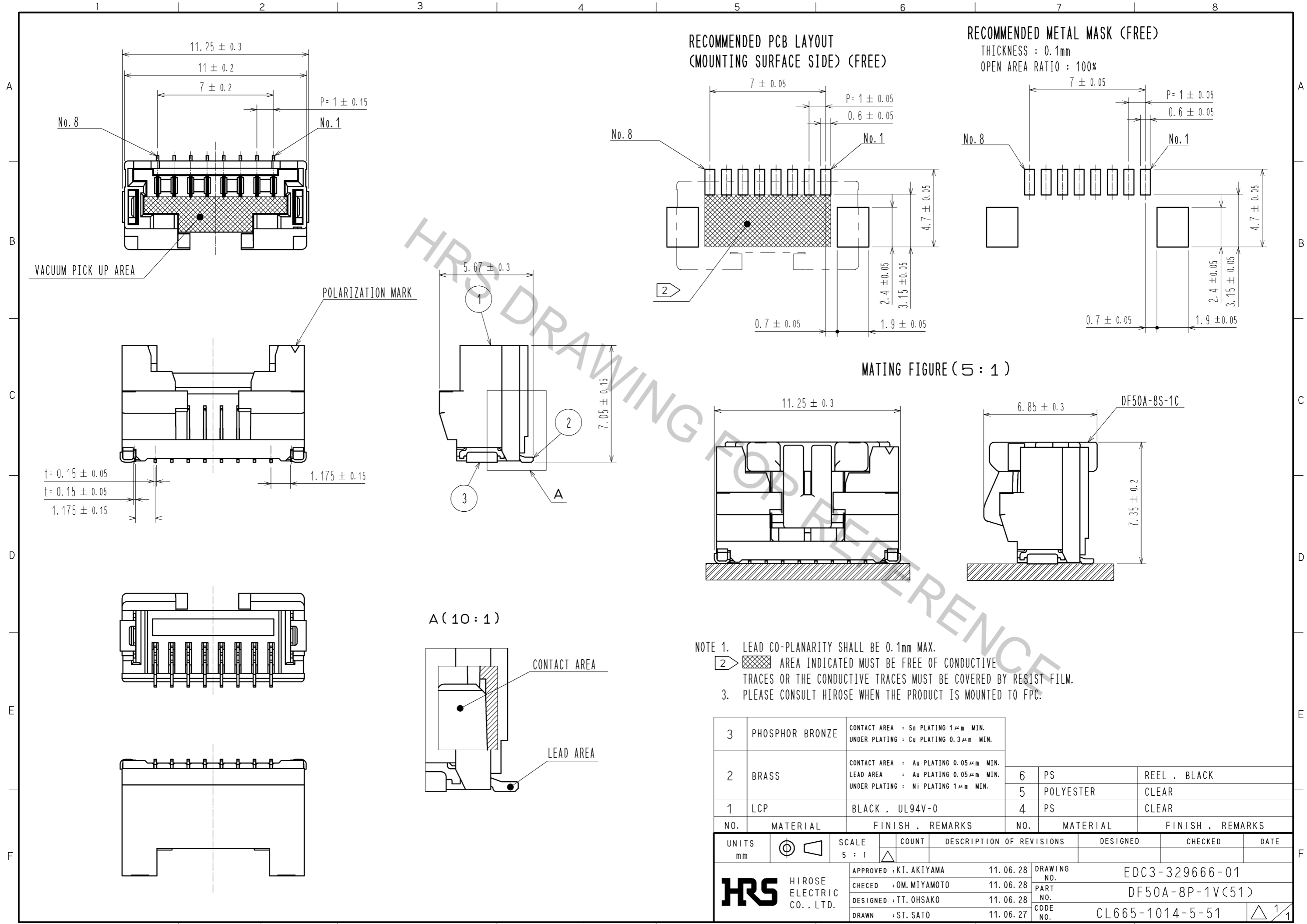
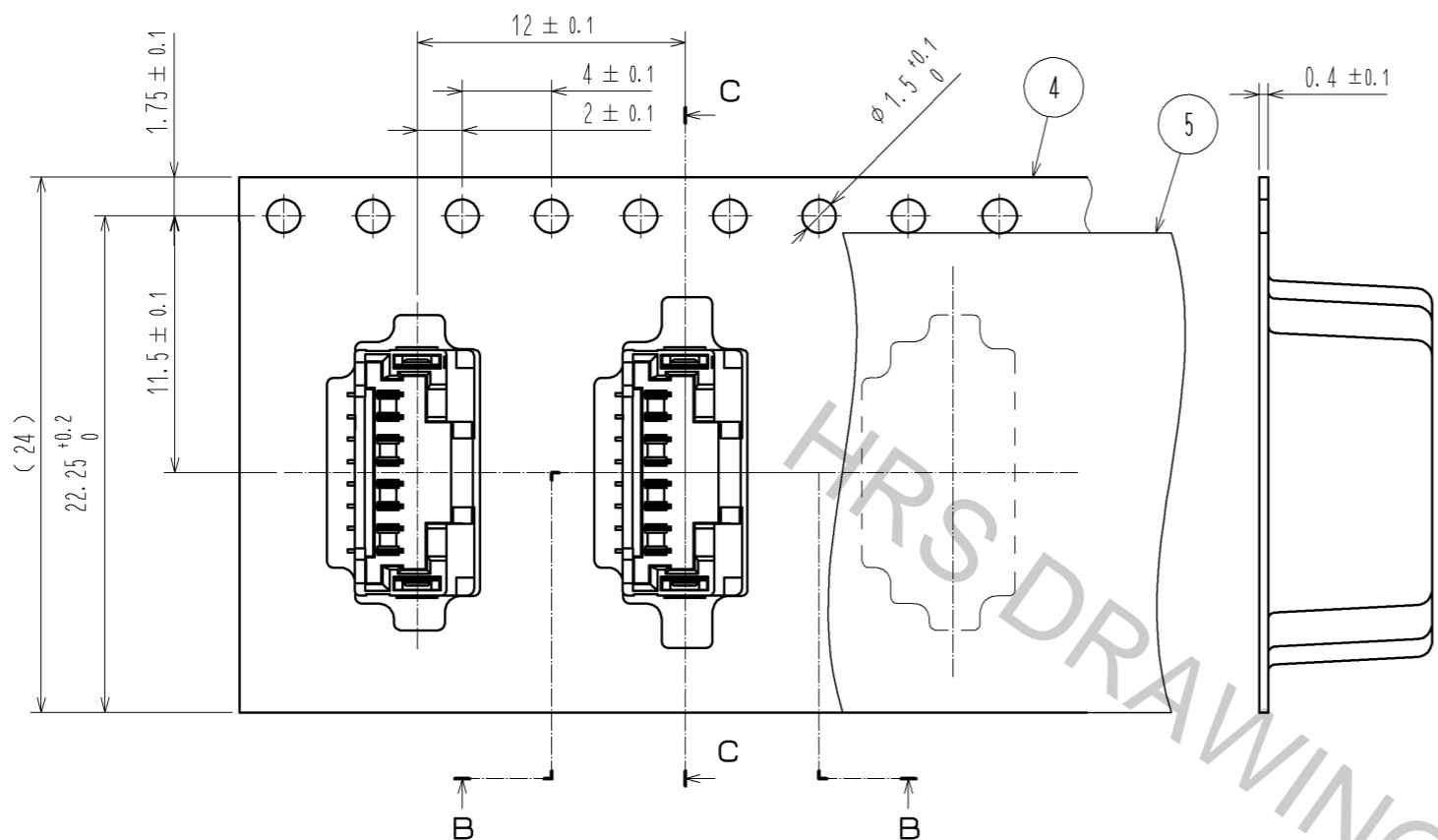


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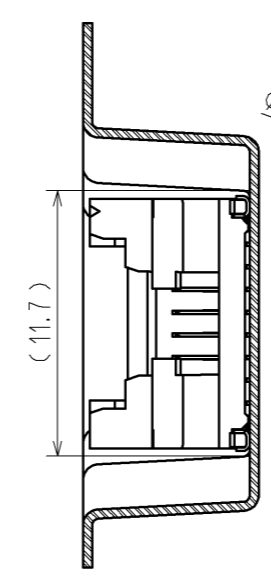


3	PHOSPHOR BRONZE	CONTACT AREA : Sn PLATING 1μm MIN. UNDER PLATING : Cu PLATING 0.3μm MIN.	6	PS	REEL . BLACK
2	BRASS	CONTACT AREA : Au PLATING 0.05μm MIN. LEAD AREA : Au PLATING 0.05μm MIN. UNDER PLATING : Ni PLATING 1μm MIN.	5	POLYESTER	CLEAR
1	LCP	BLACK , UL94V-0	4	PS	CLEAR
NO.	MATERIAL	FINISH . REMARKS	NO.	MATERIAL	FINISH . REMARKS

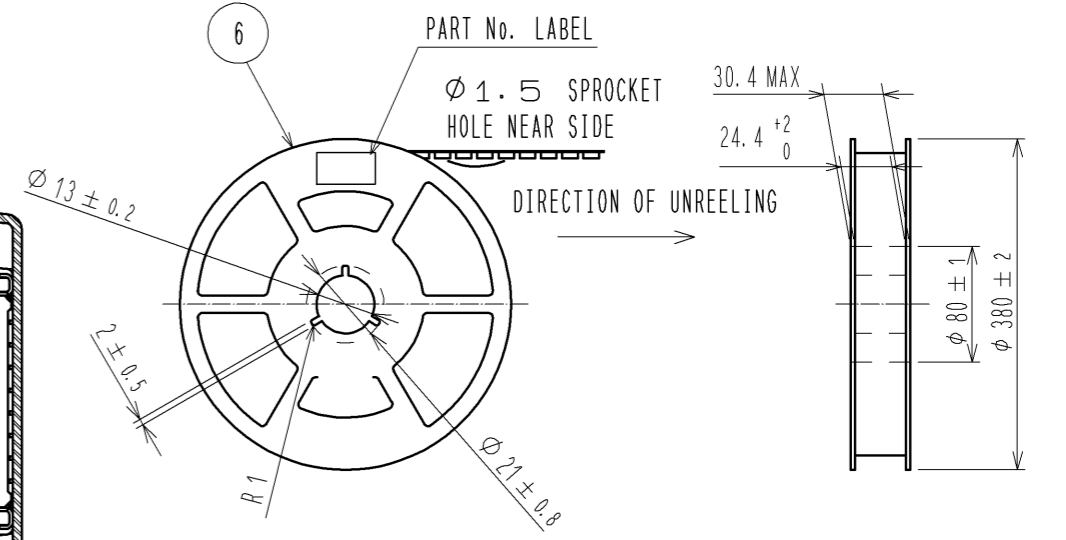
UNITS mm		SCALE 5 : 1	COUNT △	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
HIROSE ELECTRIC CO., LTD.				APPROVED : KI. AKIYAMA 11.06.28	DRAWING NO. EDC3-329666-01		
				CHECED : OM. MIYAMOTO 11.06.28	PART NO. DF50A-8P-1V(51)		
				DESIGNED : TT. OHSAKO 11.06.28	CODE NO. CL665-1014-5-51		
				DRAWN : ST. SATO 11.06.27	1/1		



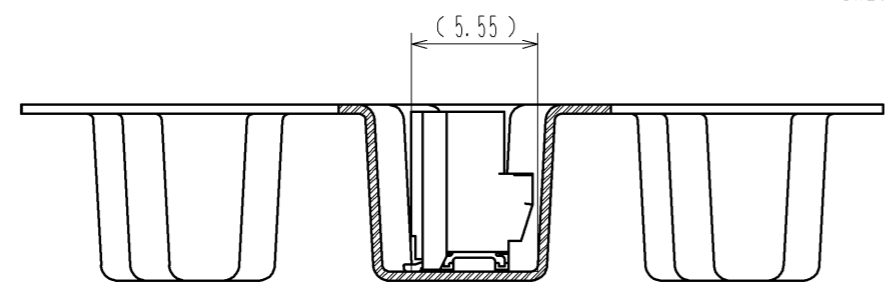
C-C (FREE)



STYLE AND DIMENSION OF REEL (FREE)



B-B (FREE)



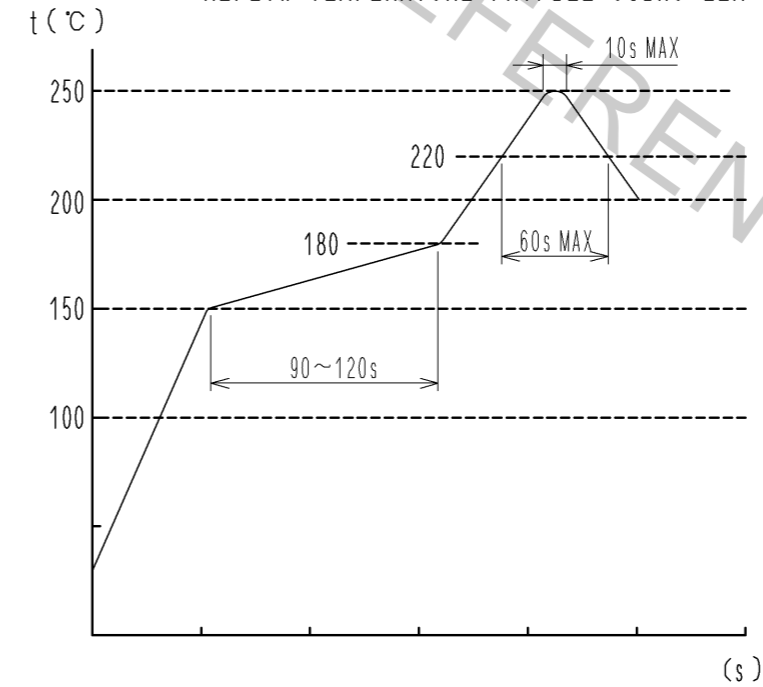
DIRECTION OF UNREELING

DETAIL OF PART No. LABEL

生産月日	年 月 日
図 番	CL665-1014-5-51
品 名	DF50A-8P-1V(51)
納入数量	1000 K0
納入者	ヒロセ電機(株)

- SUPPLIER
- QUANTITY
- PART No.
- CODE No.
- DATE OF MANUFACTURED

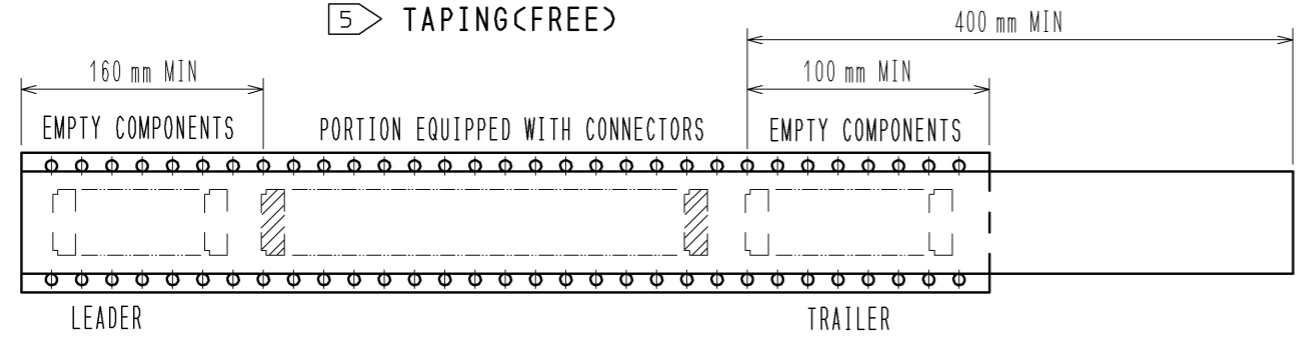
REFLOW TEMPERATURE PROFILE USING LEAD-FREE SOLDER PASTE (REFERENCE)



NUMBER OF REFLOW CYCLES 2 CYCLES MAX.
THE TEMPERATURE IS MEASURED IN THE TERMINAL LEAD PART.

ADDITIONAL FACTORS, SUCH AS SOLDER PASTE TYPE, PCB SIZE AND OTHER MOUNTED COMPONENTS COULD AFFECT THE PROFILE. THEREFORE, A THOROUGH EVALUATION OF MOUNTING CONDITION IS REQUIRED PRIOR TO PRODUCTION. TEMPERATURE IS MEASURED AT CONTACT LEAD.

5 TAPING (FREE)



NOTE 4. 1 REEL : 1000 CONNECTORS
5 REEL TO JIS C 0806. (PACKAGING OF COMPONENTS FOR AUTOMATIC HANDLING)
6. THE DIMENSIONS IN PARENTHESES ARE FOR REFERENCE.

HRS	DRAWING NO.	EDC3-329666-01
	PART NO.	DF50A-8P-1V(51)
	CODE NO.	CL665-1014-5-51
		△ 2/1